



Material Content Data Sheet



Sales Product Name		BSC010NE2LSI		Issued		2. August 2018		
MA#		MA001646220						
Package		PG-TDSON-8-7		Weight*		118.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.077	0.90	0.90	9049	9049
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	iron	7439-89-6	0.038	0.03		318	
	non noble metal	copper	7440-50-8	37.762	31.74	31.78	317392	317805
	noble metal	gold	7440-57-5	0.044	0.04	0.04	373	373
wire	organic material	carbon black	1333-86-4	0.087	0.07		728	
encapsulation	plastics	epoxy resin	-	6.148	5.17		51673	
	inorganic material	silicondioxide	60676-86-0	37.059	31.15	36.39	311491	363892
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12201	12201
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1391	1391
solder	non noble metal	tin	7440-31-5	0.030	0.02		248	
	noble metal	silver	7440-22-4	0.037	0.03		310	
	non noble metal	lead	7439-92-1	1.410	1.19	1.24	11851	12409
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	non noble metal	copper	7440-50-8	11.320	9.51	9.52	95147	95271
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	iron	7439-89-6	0.022	0.02		188	
	non noble metal	copper	7440-50-8	22.292	18.74	18.77	187365	187609
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com